HM5164800A Series
HM5165800A Series

8388608-word × 8-bit Dynamic Random Access Memory

HITACHI

ADE-203-595(Z)
Preliminary Rev. 0.0
Jun. 3, 1996

Description

The Hitachi HM5164800A Series, HM5165800A Series are CMOS dynamic RAMs organized as 8,388,608-word × 8-bit. They employ the most advanced CMOS technology for high performance and low power. The HM5164800A Series, HM5165800A Series offer Fast Page Mode as a high speed access mode. They have the package variations of standard 400-mil 32-pin plastic SOJ and standard 400-mil 32-pin plastic TSOPII.

Features

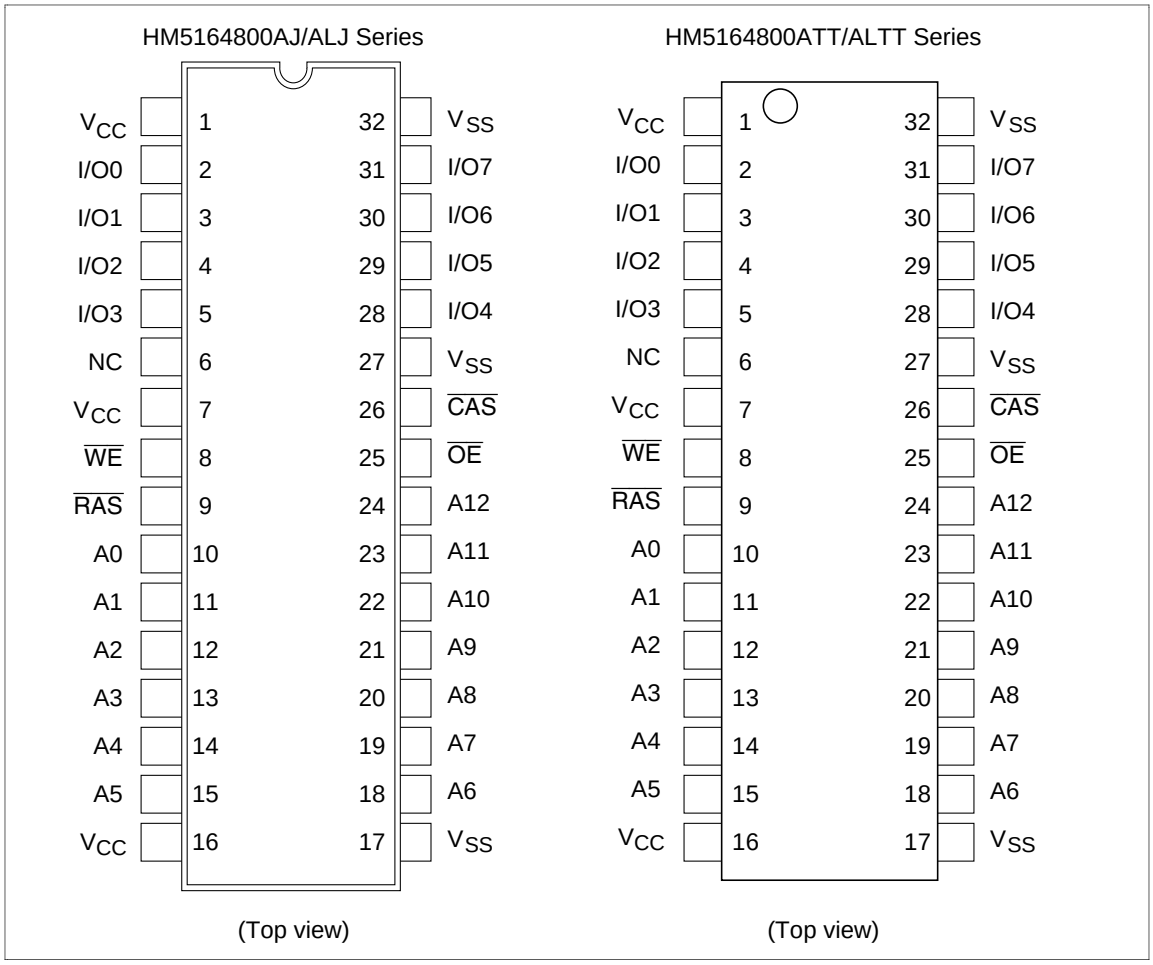
- Single 3.3 V (±0.3 V)
- High speed
  - — Access time: 50 ns/60 ns/70 ns (max)
- Low power dissipation
  - — Active mode : TBD/540 mW/468 mW (max) (HM5164800A Series)
    : TBD/666 mW/594 mW (max) (HM5165800A Series)
  - — Standby mode : 7.2 mW (max)
    : TBD (L-version)
- Fast page mode capability
- Long refresh period
  - — 8192 $\overline{\text{RAS}}$ only refresh cycles : 64 ms (HM5164800A Series)
    4096 CBR/Hidden refresh cycles : 64 ms
    : 128 ms (L-version)
  - — 4096 $\overline{\text{RAS}}$ only refresh cycles : 64 ms (HM5165800A Series)
    4096 CBR/Hidden refresh cycles : 64 ms
    : 128 ms (L-version)

- 4 variations of refresh
  - — $\overline{\text{RAS}}$-only refresh
  - — $\overline{\text{CAS}}$-before-$\overline{\text{RAS}}$ refresh
  - — Hidden refresh
  - — Self refresh (L-version)
- Battery backup operation (L-version)

Ordering Information

Type No.	Access time	Package
HM5164800AJ-5	50 ns	400-mil 32-pin plastic SOJ (CP-32DC)
HM5164800AJ-6	60 ns	
HM5164800AJ-7	70 ns	
HM5164800ALJ-5	50 ns	
HM5164800ALJ-6	60 ns	
HM5164800ALJ-7	70 ns	
HM5165800AJ-5	50 ns	
HM5165800AJ-6	60 ns	
HM5165800AJ-7	70 ns	
HM5165800ALJ-5	50 ns	
HM5165800ALJ-6	60 ns	
HM5165800ALJ-7	70 ns	
HM5164800ATT-5	50 ns	400-mil 32-pin plastic TSOP II (TTP-32DC)
HM5164800ATT-6	60 ns	
HM5164800ATT-7	70 ns	
HM5164800ALTT-5	50 ns	
HM5164800ALTT-6	60 ns	
HM5164800ALTT-7	70 ns	
HM5165800ATT-5	50 ns	
HM5165800ATT-6	60 ns	
HM5165800ATT-7	70 ns	
HM5165800ALTT-5	50 ns	
HM5165800ALTT-6	60 ns	
HM5165800ALTT-7	70 ns	

Pin Arrangement

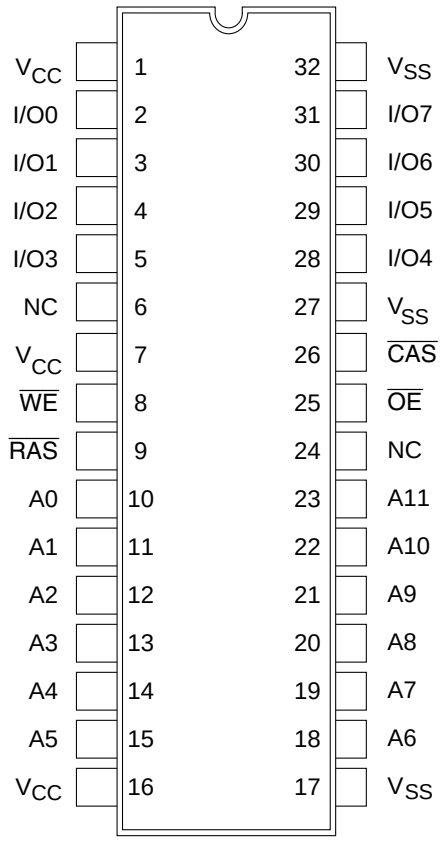


Pin Description

Pin name	Function
A0 to A12	Address input • Row/Refresh address A0 to A12 • Column address A0 to A9
I/O0 to I/O7	Data input/Data output
$\overline{RAS}$	Row address strobe
$\overline{CAS}$	Column address strobe
$\overline{WE}$	Read/Write enable
$\overline{OE}$	Output enable
V_{cc}	Power supply
V_{ss}	Ground
NC	No connection

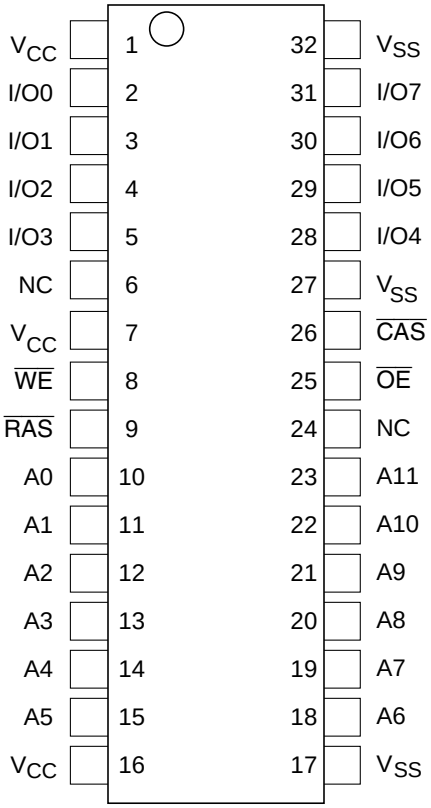
Pin Arrangement

HM5165800AJ/ALJ Series



(Top view)

HM5165800ATT/ALTT Series

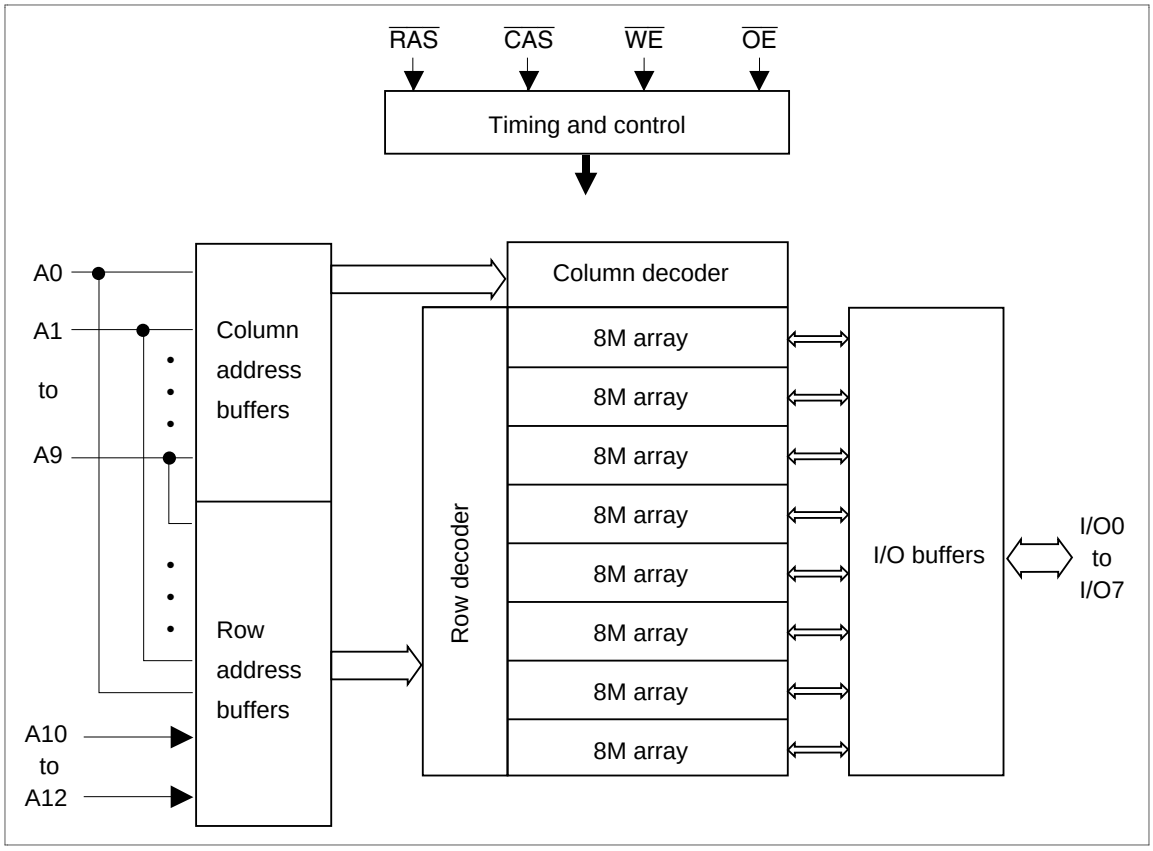


(Top view)

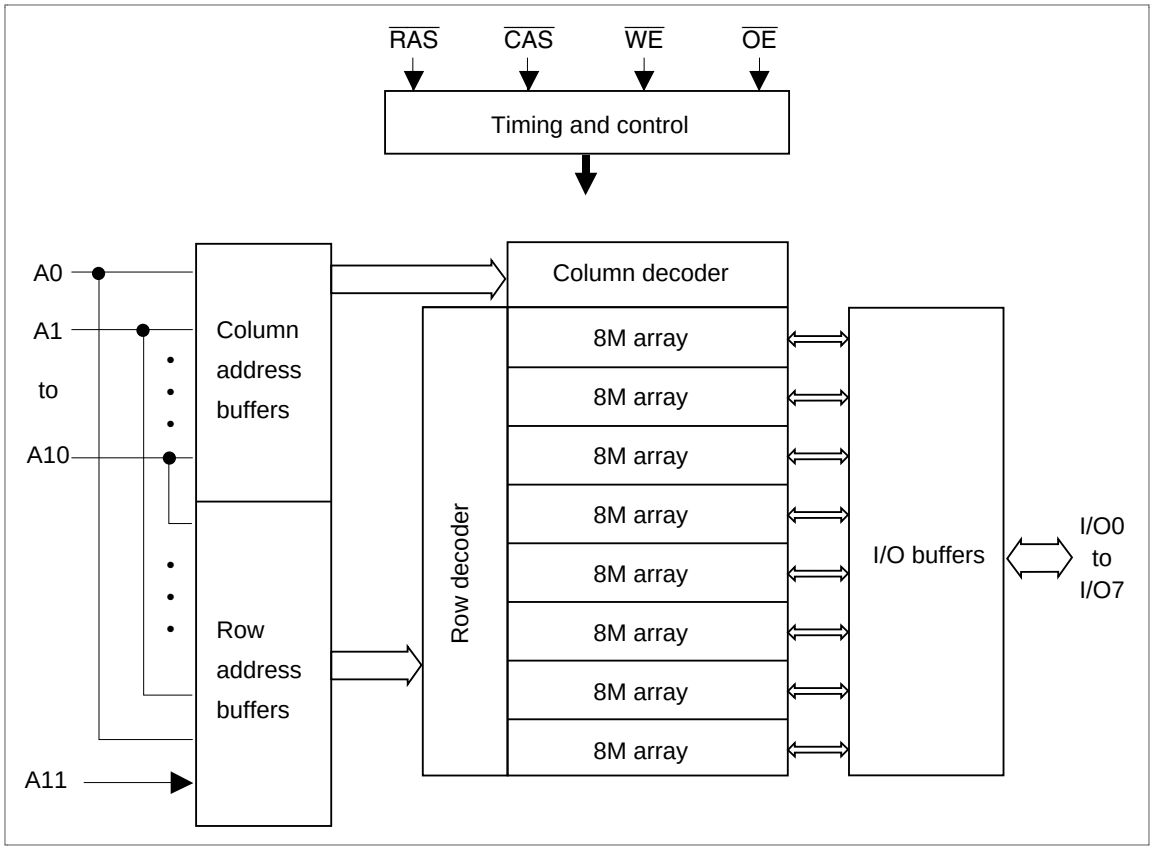
Pin Description

Pin name	Function
A0 to A11	Address input • Row/Refresh address A0 to A11 • Column address A0 to A10
I/O0 to I/O7	Data input/Data output
$\overline{RAS}$	Row address strobe
$\overline{CAS}$	Column address strobe
$\overline{WE}$	Read/Write enable
$\overline{OE}$	Output enable
V_{CC}	Power supply
V_{SS}	Ground
NC	No connection

Block Diagram (HM5164800A Series)



Block Diagram (HM5165800A Series)



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	–0.5 to V_{CC} + 0.5 (≤ 4.6 V (max))	V
Supply voltage relative to V_{SS}	V_{CC}	–0.5 to +4.6	V
Short circuit output current	Iout	50	mA
Power dissipation	P_T	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	–55 to +125	°C

Recommended DC Operating Conditions (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Supply voltage	V_{CC}	3.0	3.3	3.6	V	1, 2
Input high voltage	V_{IH}	2.0	—	V_{CC} + 0.3	V	1
Input low voltage	V_{IL}	–0.3	—	0.8	V	1

Notes: 1. All voltage referred to V_{SS}

2. The supply voltage with all V_{CC} pins must be on the same level. The supply voltage with all V_{SS} pins must be on the same level.

DC Characteristics

(Ta = 0 to +70°C, V_{CC} = 3.3 V ± 0.3 V, V_{SS} = 0 V) (HM5164800A Series)

		HM5164800A							
		-5		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Test conditions**
Operating current*1, *2	I_{CC1}	—	TBD	—	135	—	115	mA	t_{RC} = min
Standby current	I_{CC2}	—	TBD	—	2	—	2	mA	TTL interface $\overline{RAS}$, $\overline{CAS}$ = V_{IH} Dout = High-Z
		—	TBD	—	1	—	1	mA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
Standby current (L-version)	I_{CC2}	—	TBD	—	TBD	—	TBD	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
$\overline{RAS}$-only refresh current*2	I_{CC3}	—	TBD	—	135	—	115	mA	t_{RC} = min
Standby current*1	I_{CC5}	—	TBD	—	5	—	5	mA	$\overline{RAS}$ = V_{IH}, $\overline{CAS}$ = V_{IL} Dout = enable
$\overline{CAS}$-before-$\overline{RAS}$ refresh current	I_{CC6}	—	TBD	—	150	—	130	mA	t_{RC} = min
Fast page mode current*1, *3	I_{CC7}	—	TBD	—	125	—	115	mA	t_{PC} = min
Battery backup current*4 (Standby with CBR refresh) (L-version)	I_{CC10}	—	TBD	—	TBD	—	TBD	µA	CMOS interface Dout = High-Z, CBR refresh: t_{RC} = 31.3 µs t_{RAS} ≤ 0.3 µs
Self refresh mode current (L-version)	I_{CC11}	—	TBD	—	TBD	—	TBD	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≤ 0.2 V Dout = High-Z
Input leakage current	I_{LI}	TBD	TBD	–10	10	–10	10	µA	0 V ≤ Vin ≤ V_{CC} + 0.3 V
Output leakage current	I_{LO}	TBD	TBD	–10	10	–10	10	µA	0 V ≤ Vin ≤ V_{CC} + 0.3 V Dout = disable
Output high voltage	V_{OH}	TBD	TBD	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = –2 mA
Output low voltage	V_{OL}	TBD	TBD	0	0.4	0	0.4	V	Low Iout = 2 mA

Notes: 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.

2. Address can be changed once or less while $\overline{RAS}$ = V_{IL}.
3. Address can be changed once or less within one page mode cycle t_{PC}.
4. V_{IH} ≥ V_{CC} – 0.2 V, 0 V ≤ V_{IL} ≤ 0.2 V.

DC Characteristics

(Ta = 0 to +70°C, V_{CC} = 3.3 V ± 0.3 V, V_{SS} = 0 V) (HM5165800A Series)

		HM5165800A							
		-5		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Test conditions**
Operating current*1, *2	I_{CC1}	—	TBD	—	185	—	165	mA	t_{RC} = min
Standby current	I_{CC2}	—	TBD	—	2	—	2	mA	TTL interface $\overline{RAS}$, $\overline{CAS}$ = V_{IH} Dout = High-Z
		—	TBD	—	1	—	1	mA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
Standby current (L-version)	I_{CC2}	—	TBD	—	TBD	—	TBD	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Dout = High-Z
$\overline{RAS}$-only refresh current*2	I_{CC3}	—	TBD	—	185	—	165	mA	t_{RC} = min
Standby current*1	I_{CC5}	—	TBD	—	5	—	5	mA	$\overline{RAS}$ = V_{IH}, $\overline{CAS}$ = V_{IL} Dout = enable
$\overline{CAS}$-before-$\overline{RAS}$ refresh current	I_{CC6}	—	TBD	—	150	—	130	mA	t_{RC} = min
Fast page mode current*1, *3	I_{CC7}	—	TBD	—	125	—	115	mA	t_{PC} = min
Battery backup current*4 (Standby with CBR refresh) (L-version)	I_{CC10}	—	TBD	—	TBD	—	TBD	µA	CMOS interface Dout = High-Z, CBR refresh: t_{RC} = 31.3 µs t_{RAS} ≤ 0.3 µs
Self refresh mode current (L-version)	I_{CC11}	—	TBD	—	TBD	—	TBD	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≤ 0.2 V Dout = High-Z
Input leakage current	I_{LI}	TBD	TBD	–10	10	–10	10	µA	0 V ≤ Vin ≤ V_{CC} + 0.3 V
Output leakage current	I_{LO}	TBD	TBD	–10	10	–10	10	µA	0 V ≤ Vin ≤ V_{CC} + 0.3 V Dout = disable
Output high voltage	V_{OH}	TBD	TBD	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = –2 mA
Output low voltage	V_{OL}	TBD	TBD	0	0.4	0	0.4	V	Low Iout = 2 mA

Notes: 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.

2. Address can be changed once or less while $\overline{RAS}$ = V_{IL}.
3. Address can be changed once or less within one page mode cycle t_{PC}.
4. V_{IH} ≥ V_{CC} – 0.2 V, 0 V ≤ V_{IL} ≤ 0.2 V.

Capacitance ($Ta = 25°C$, $V_{CC} = 3.3\ V \pm 0.3\ V$)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C_{I1}	—	5	pF	1
Input capacitance (Clocks)	C_{I2}	—	7	pF	1
Output capacitance (Data-in, Data-out)	$C_{I/O}$	—	7	pF	1, 2

Notes : 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
2. $\overline{RAS}$, $\overline{CAS}$ = V_{IH} to disable Dout.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 3.3 V ± 0.3 V, V_{SS} = 0 V) *1, *2, *17

Test Conditions

- Input rise and fall time: 5 ns
- Input timing reference levels: 0.8 V, 2.0 V
- Output timing reference levels: 0.8 V, 2.0 V
- Output load: 1 TTL gate + C_L (100 pF) (Including scope and jig)

Read, Write, Read-Modify-Write and Refresh Cycles (Common parameters)

		HM5164800A/HM5165800A							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t_{RC}	TBD	—	110	—	130	—	ns	
$\overline{RAS}$ precharge time	t_{RP}	TBD	—	40	—	50	—	ns	
$\overline{CAS}$ precharge time	t_{CP}	TBD	—	10	—	10	—	ns	
$\overline{RAS}$ pulse width	t_{RAS}	TBD	TBD	60	10000	70	10000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	TBD	TBD	15	10000	18	10000	ns	
Row address setup time	t_{ASR}	TBD	—	0	—	0	—	ns	
Row address hold time	t_{RAH}	TBD	—	10	—	10	—	ns	
Column address setup time	t_{ASC}	TBD	—	0	—	0	—	ns	
Column address hold time	t_{CAH}	TBD	—	10	—	15	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	TBD	TBD	20	45	20	52	ns	3
$\overline{RAS}$ to column address delay time	t_{RAD}	TBD	TBD	15	30	15	35	ns	4
$\overline{RAS}$ hold time	t_{RSH}	TBD	—	15	—	18	—	ns	
$\overline{CAS}$ hold time	t_{CSH}	TBD	—	60	—	70	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	TBD	—	5	—	5	—	ns	
$\overline{OE}$ to Din delay time	t_{OED}	TBD	—	15	—	18	—	ns	5
$\overline{OE}$ delay time from Din	t_{DZO}	TBD	—	0	—	0	—	ns	6
$\overline{CAS}$ delay time from Din	t_{DZC}	TBD	—	0	—	0	—	ns	6
Transition time (rise and fall)	t_T	TBD	TBD	3	50	3	50	ns	7

Read Cycle

		HM5164800A/HM5165800A							
		-5		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Access time from $\overline{RAS}$	t_{RAC}	—	TBD	—	60	—	70	ns	8, 9
Access time from $\overline{CAS}$	t_{CAC}	—	TBD	—	15	—	18	ns	9, 10, 16
Access time from address	t_{AA}	—	TBD	—	30	—	35	ns	9, 11, 16
Access time from $\overline{OE}$	t_{OEA}	—	TBD	—	15	—	18	ns	9, 19
Read command setup time	t_{RCS}	TBD	—	0	—	0	—	ns	
Read command hold time to $\overline{CAS}$	t_{RCH}	TBD	—	0	—	0	–	ns	12
Read command hold time to $\overline{RAS}$	t_{RRH}	TBD	—	5	—	5	—	ns	12
Column address to $\overline{RAS}$ lead time	t_{RAL}	TBD	—	30	—	35	—	ns	
Column address to $\overline{CAS}$ lead time	t_{CAL}	TBD	—	30	—	35	—	ns	
$\overline{CAS}$ to output in low-Z	t_{CLZ}	TBD	—	0	—	0	—	ns	
Output data hold time	t_{OH}	TBD	—	3	—	3	—	ns	
Output data hold time from $\overline{OE}$	t_{OHO}	TBD	—	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	TBD	—	15	—	15	ns	13
Output buffer turn-off to $\overline{OE}$	t_{OEZ}	—	TBD	—	15	—	15	ns	13
$\overline{CAS}$ to Din delay time	t_{CDD}	TBD	—	15	—	18	—	ns	5

Write Cycle

		HM5164800A/HM5165800A							
		-5		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Write command setup time	t_{WCS}	TBD	—	0	—	0	—	ns	14
Write command hold time	t_{WCH}	TBD	—	10	—	15	—	ns	
Write command pulse width	t_{WP}	TBD	—	10	—	10	—	ns	
Write command to $\overline{RAS}$ lead time	t_{RWL}	TBD	—	15	—	18	—	ns	
Write command to $\overline{CAS}$ lead time	t_{CWL}	TBD	—	15	—	18	—	ns	
Data-in setup time	t_{DS}	TBD	—	0	—	0	—	ns	
Data-in hold time	t_{DH}	TBD	—	10	—	15	—	ns	

Read-Modify-Write Cycle

		HM5164800A/HM5165800A							
		-5		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Read-modify-write cycle time	t_{RWC}	TBD	—	155	—	181	—	ns	
$\overline{RAS}$ to $\overline{WE}$ delay time	t_{RWD}	TBD	—	85	—	98	—	ns	14
$\overline{CAS}$ to $\overline{WE}$ delay time	t_{CWD}	TBD	—	40	—	46	—	ns	14
Column address to $\overline{WE}$ delay time	t_{AWD}	TBD	—	55	—	63	—	ns	14
$\overline{OE}$ hold time from $\overline{WE}$	t_{OEH}	TBD	—	15	—	18	—	ns	

Refresh Cycle

		HM5164800A/HM5165800A							
		-5		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
$\overline{CAS}$ setup time (CBR refresh cycle)	t_{CSR}	TBD	—	5	—	5	—	ns	
$\overline{CAS}$ hold time (CBR refresh cycle)	t_{CHR}	TBD	—	10	—	10	—	ns	
$\overline{WE}$ setup time (CBR refresh cycle)	t_{WRP}	TBD	—	0	—	0	—	ns	
$\overline{WE}$ hold time (CBR refresh cycle)	t_{WRH}	TBD	—	10	—	10	—	ns	
$\overline{RAS}$ precharge to $\overline{CAS}$ hold time	t_{RPC}	TBD	—	0	—	0	—	ns	

Fast Page Mode Cycle

		HM5164800A/HM5165800A							
		-5		-6		-7			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Fast page mode cycle time	t_{PC}	TBD	—	40	—	45	—	ns	
Fast page mode $\overline{RAS}$ pulse width	t_{RASP}	—	TBD	—	100000	—	100000	ns	15
Access time from $\overline{CAS}$ precharge	t_{CPA}	—	TBD	—	35	—	40	ns	9, 16
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{CPRH}	TBD	—	35	—	40	—	ns	

Fast Page Mode Read-Modify-Write Cycle

		HM5164800A/HM5165800A							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Fast page mode read-modify-write cycle time	t_{PRWC}	TBD	—	85	—	96	—	ns	
$\overline{WE}$ delay time from $\overline{CAS}$ precharge	t_{CPW}	TBD	—	60	—	68	—	ns	14

Refresh (HM5164800A Series)

Parameter	Symbol	Max	Unit	Note
Refresh period	t_{REF}	64	ms	8192 cycles
Refresh period (L-version)	t_{REF}	128	ms	4096 cycles

Refresh (HM5165800A Series)

Parameter	Symbol	Max	Unit	Note
Refresh period	t_{REF}	64	ms	4096 cycles
Refresh period (L-version)	t_{REF}	128	ms	4096 cycles

Self Refresh Mode (L-version)

		HM5164800AL/HM5165800AL							
		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
$\overline{RAS}$ pulse width (Self refresh)	t_{RASS}	TBD	—	100	—	100	—	µs	20
$\overline{RAS}$ precharge time (Self refresh)	t_{RPS}	TBD	—	110	—	130	—	ns	
$\overline{CAS}$ hold time (Self refresh)	t_{CHS}	TBD	—	–50	—	–50	—	ns	

Notes: 1. AC measurements assume t_T = 5 ns.

2. An initial pause of 200 µs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{RAS}$-only refresh or $\overline{CAS}$-before-$\overline{RAS}$ refresh).
3. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
4. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA}.

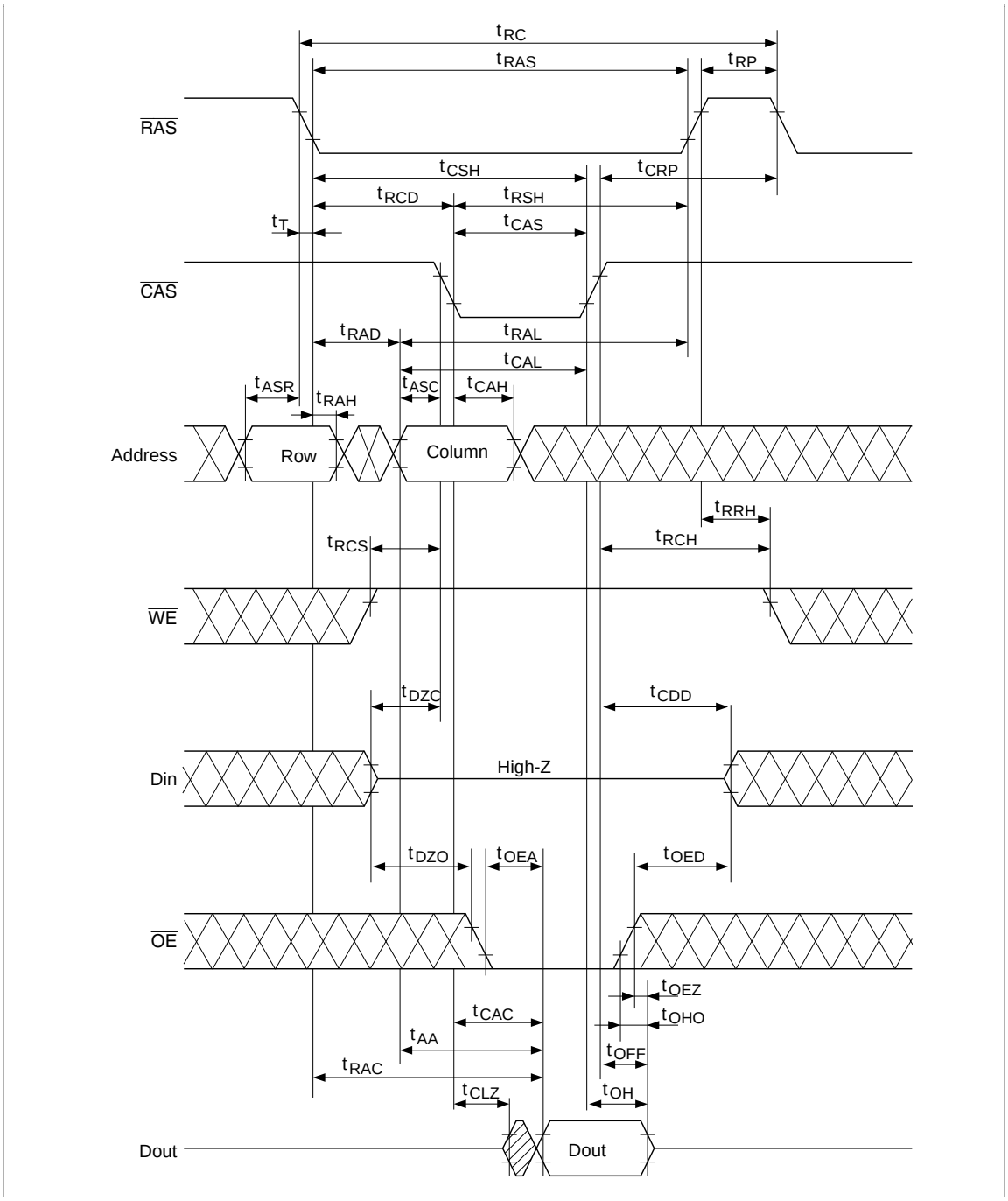
5. Either t_{OED} or t_{CDD} must be satisfied.
6. Either t_{DZO} or t_{DZC} must be satisfied.
7. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
8. Assumes that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
9. Measured with a load circuit equivalent to 1 TTL loads and 100 pF.
10. Assumes that $t_{RCD} \geq t_{RCD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\geq t_{RAD} + t_{AA}$ (max).
11. Assumes that $t_{RAD} \geq t_{RAD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\leq t_{RAD} + t_{AA}$ (max).
12. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
13. t_{OFF} (max) and t_{OEZ} (max) define the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
14. t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD}$ (min), $t_{CWD} \geq t_{CWD}$ (min), and $t_{AWD} \geq t_{AWD}$ (min), or $t_{CWD} \geq t_{CWD}$ (min), $t_{AWD} \geq t_{AWD}$ (min) and $t_{CPW} \geq t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
15. t_{RASP} defines $\overline{RAS}$ pulse width in fast page mode cycles.
16. Access time is determined by the longest among t_{AA}, t_{CAC} and t_{CPA}.
17. All the V_{CC} and V_{SS} pins shall be supplied with the same voltages.
18. In delayed write or read-modify-write cycles, $\overline{OE}$ must disable output buffer prior to applying data to the device.
19. When output buffers are enabled once, sustain the low impedance state until valid data is obtained. When output buffer is turned on and off within a very short time, generally it causes large V_{CC}/V_{SS} line noise, which causes to degrade V_{IH} min/V_{IL} max level.
20. Please do not use t_{RASS} timing, 10 µs $\leq t_{RASS} \leq$ 100 µs. During this period, the device is in transition state from normal operation mode to self refresh mode. If $t_{RASS} \geq$ 100 µs, then $\overline{RAS}$ precharge time should use t_{RPS} instead of t_{RP}.
21. CBR burst refresh or 4096 cycles of distributed CBR refresh with 15.6 µs interval should be executed within 64 ms immediately after exiting from and before entering into the self refresh mode.
22. Repetitive self refresh mode without refreshing all memory is not allowed. Once you exit from self refresh mode, all memory cells need to be refreshed before re-entering the self refresh mode again.
23. XXX: H or L (H: V_{IH} (min) $\leq V_{IN} \leq V_{IH}$ (max), L: V_{IL} (min) $\leq V_{IN} \leq V_{IL}$ (max))

    ///: Invalid Dout

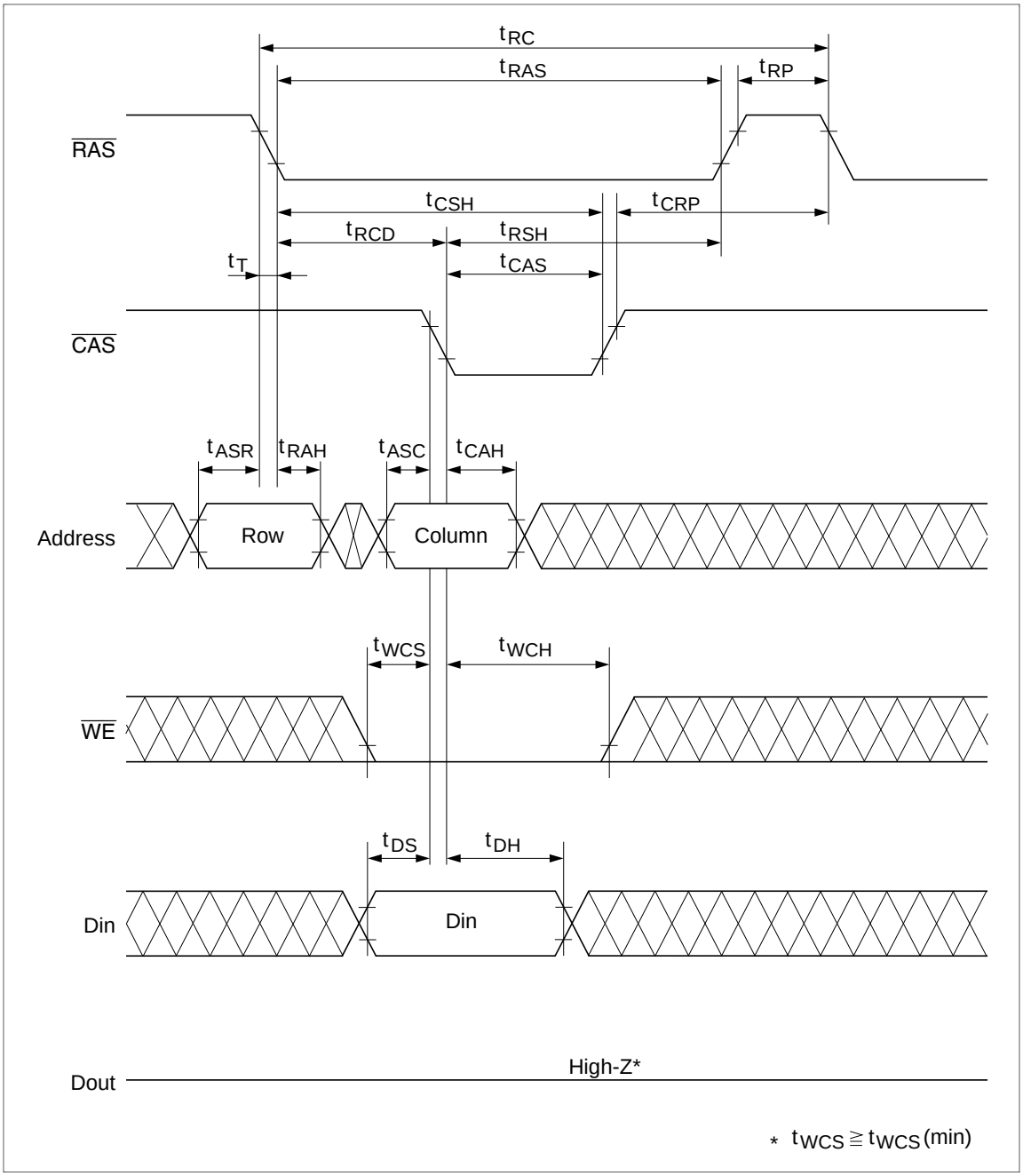
    When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL}.

Timing Waveforms*[23]

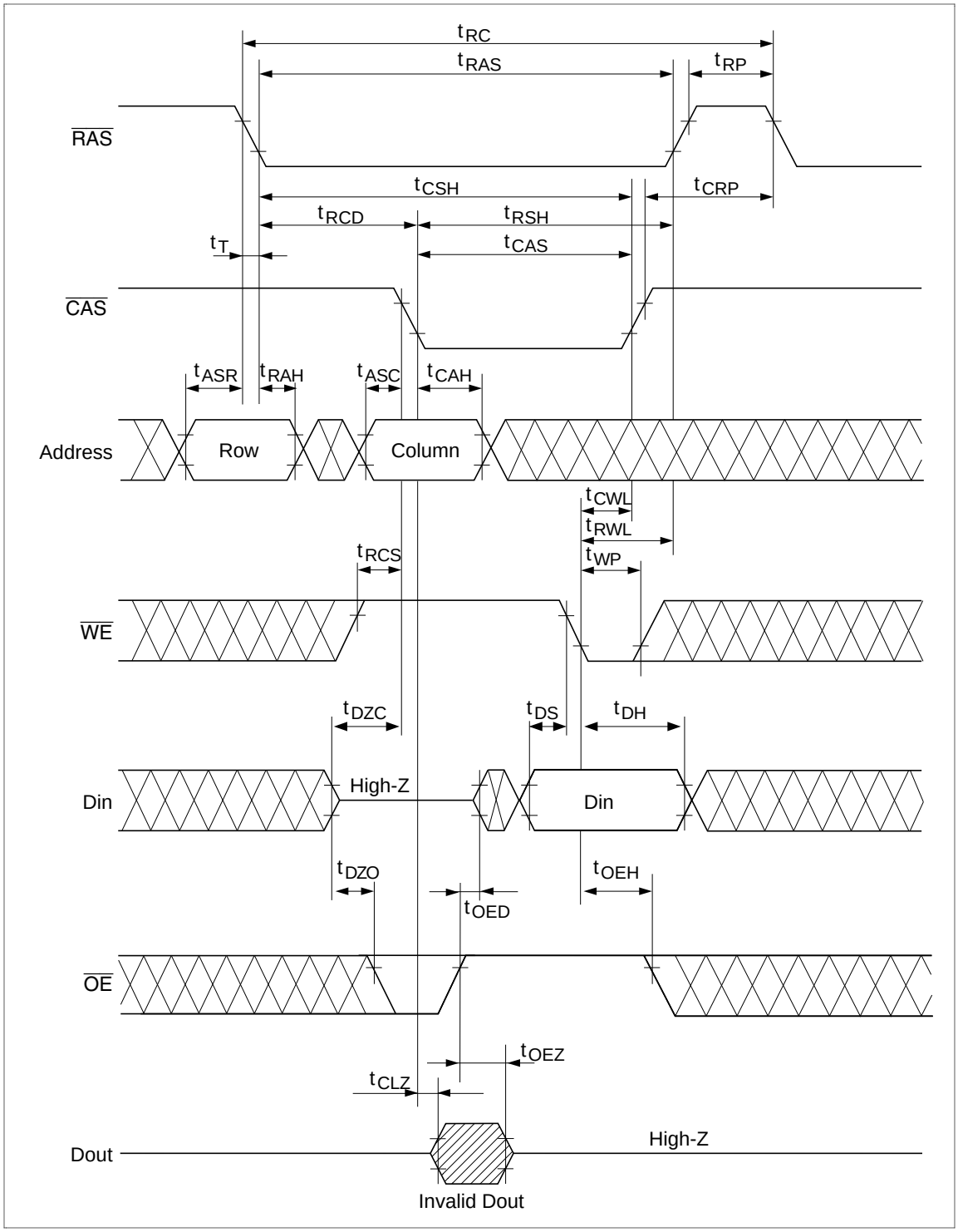
Read Cycle



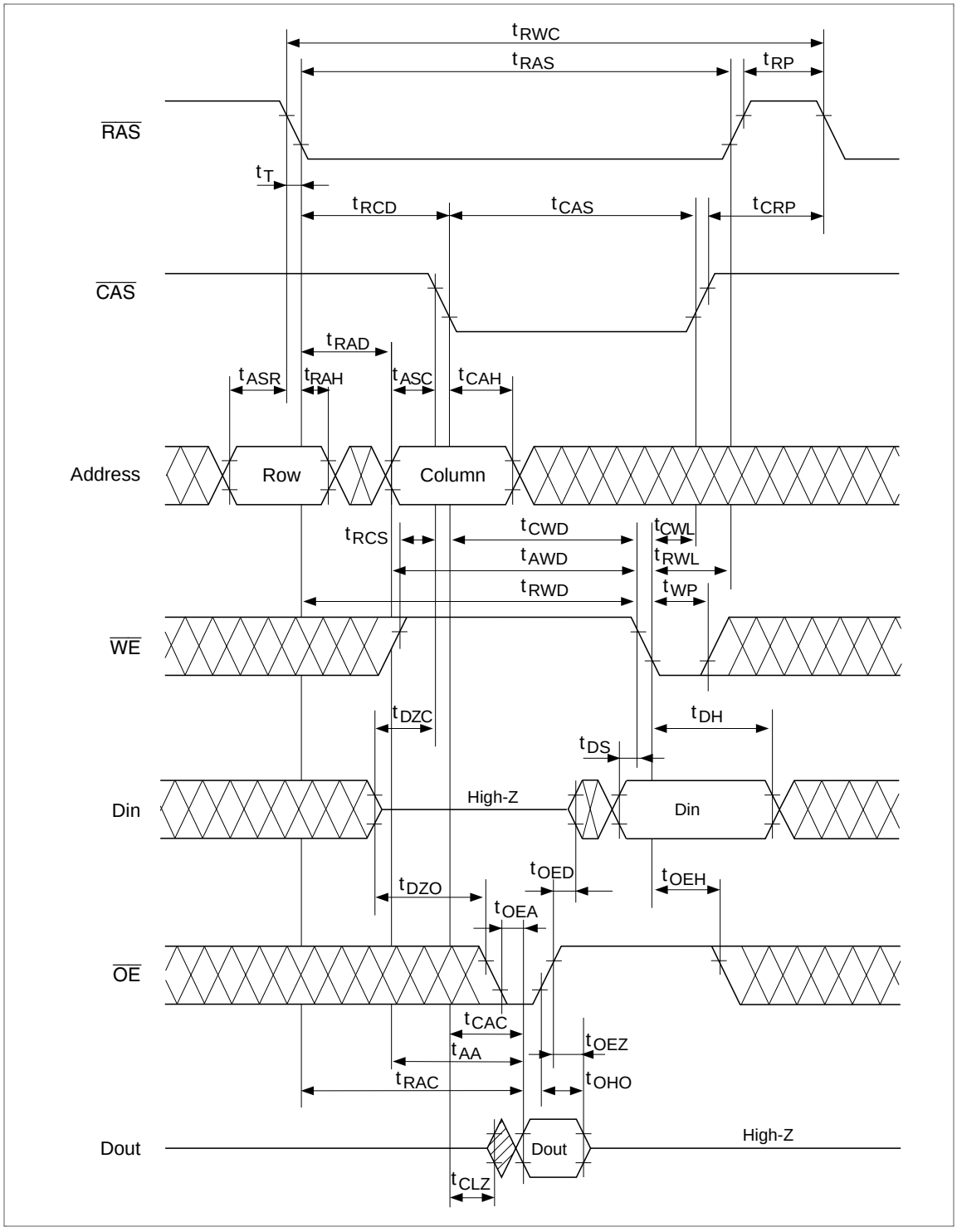
Early Write Cycle



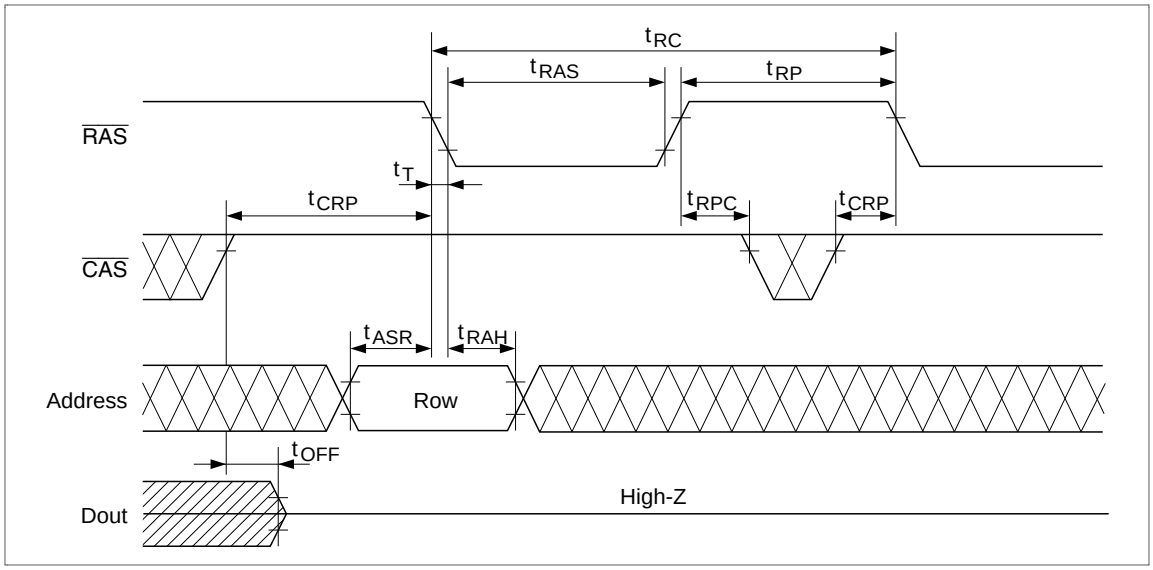
Delayed Write Cycle*[18]



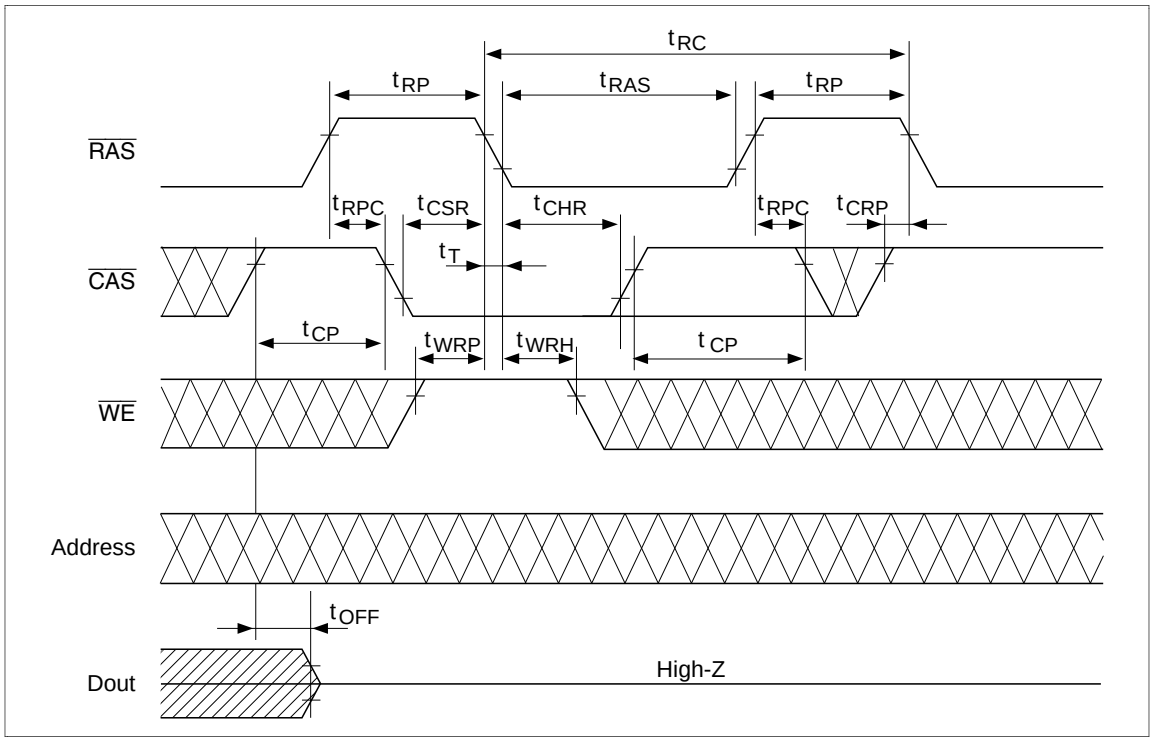
Read-Modify-Write Cycle*[18]



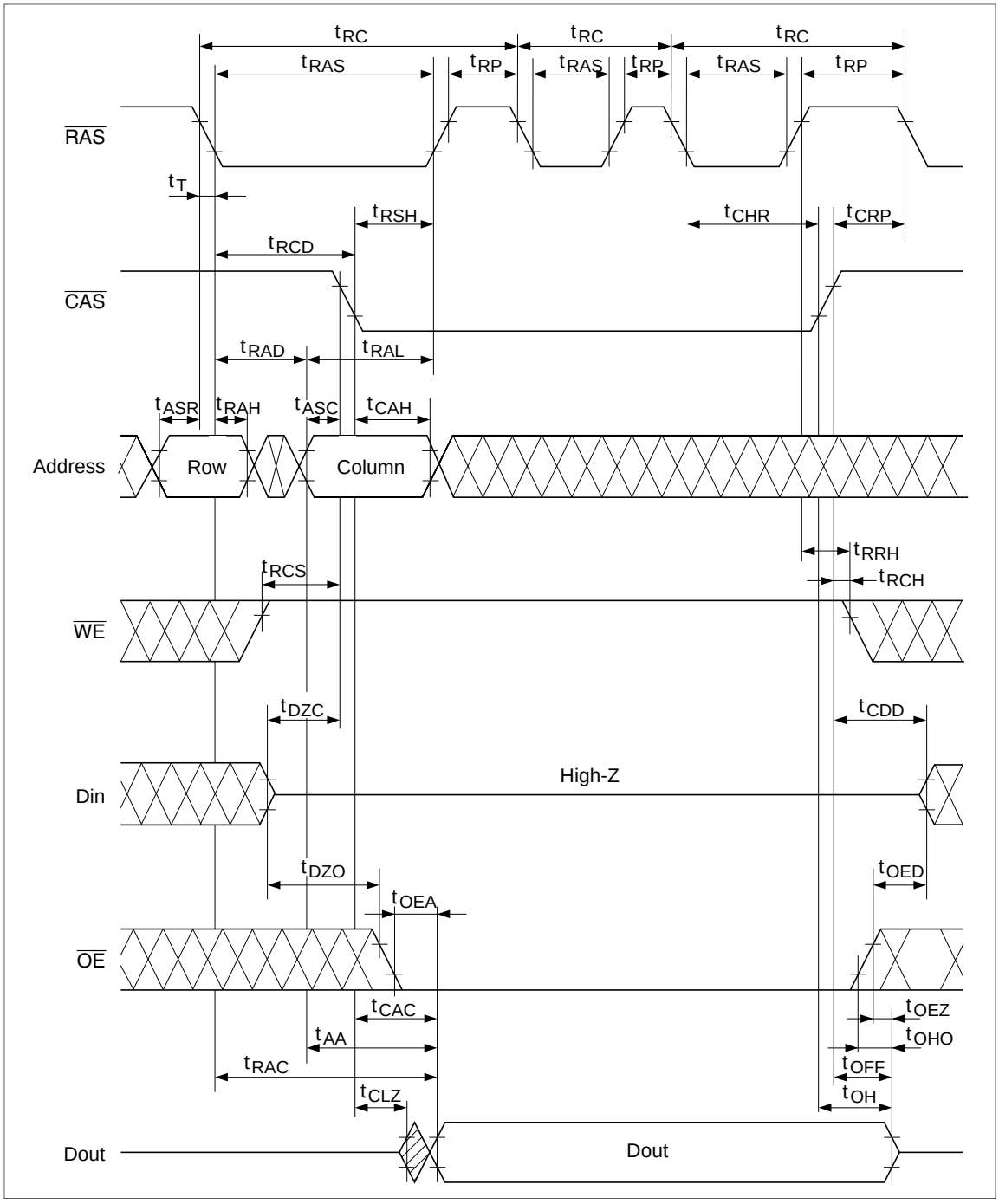
$\overline{\text{RAS}}$-Only Refresh Cycle



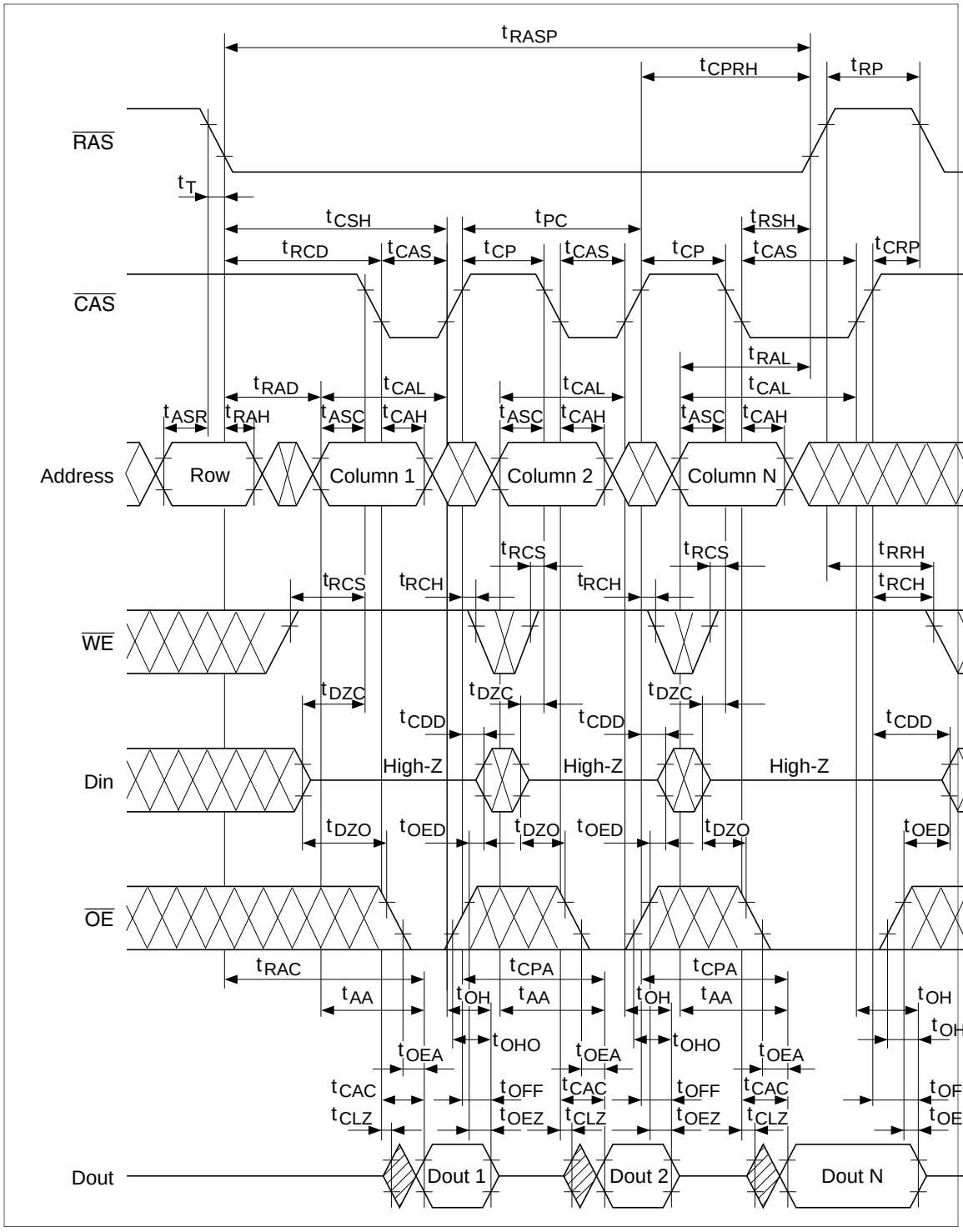
$\overline{\text{CAS}}$-Before-$\overline{\text{RAS}}$ Refresh Cycle



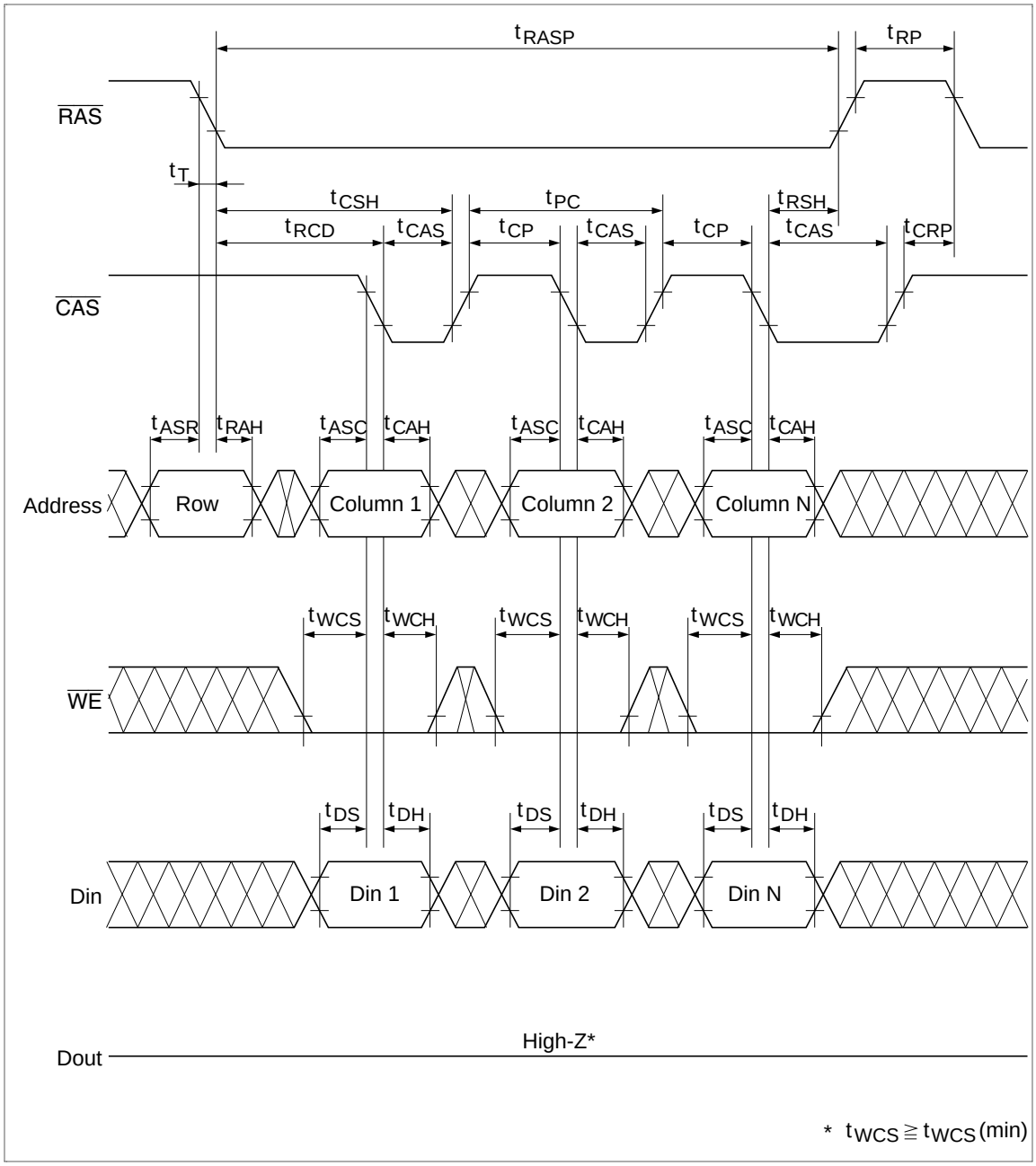
Hidden Refresh Cycle


tRC
tRC
tRC
tRAS
tRP
tRAS
tRP
tRAS
tRP
RAS
tT
tRSH
tCHR
tCRP
tRCD
CAS
tRAD
tRAL
tASR
tRAH
tASC
tCAH
Address
Row
Column
tRRH
tRCS
tRCH
WE
tDZC
tCDD
Din
High-Z
tDZO
tOEA
tOED
OE
tCAC
tOEZ
tAA
tOHO
tRAC
tOFF
tCLZ
tOH
Dout
Dout

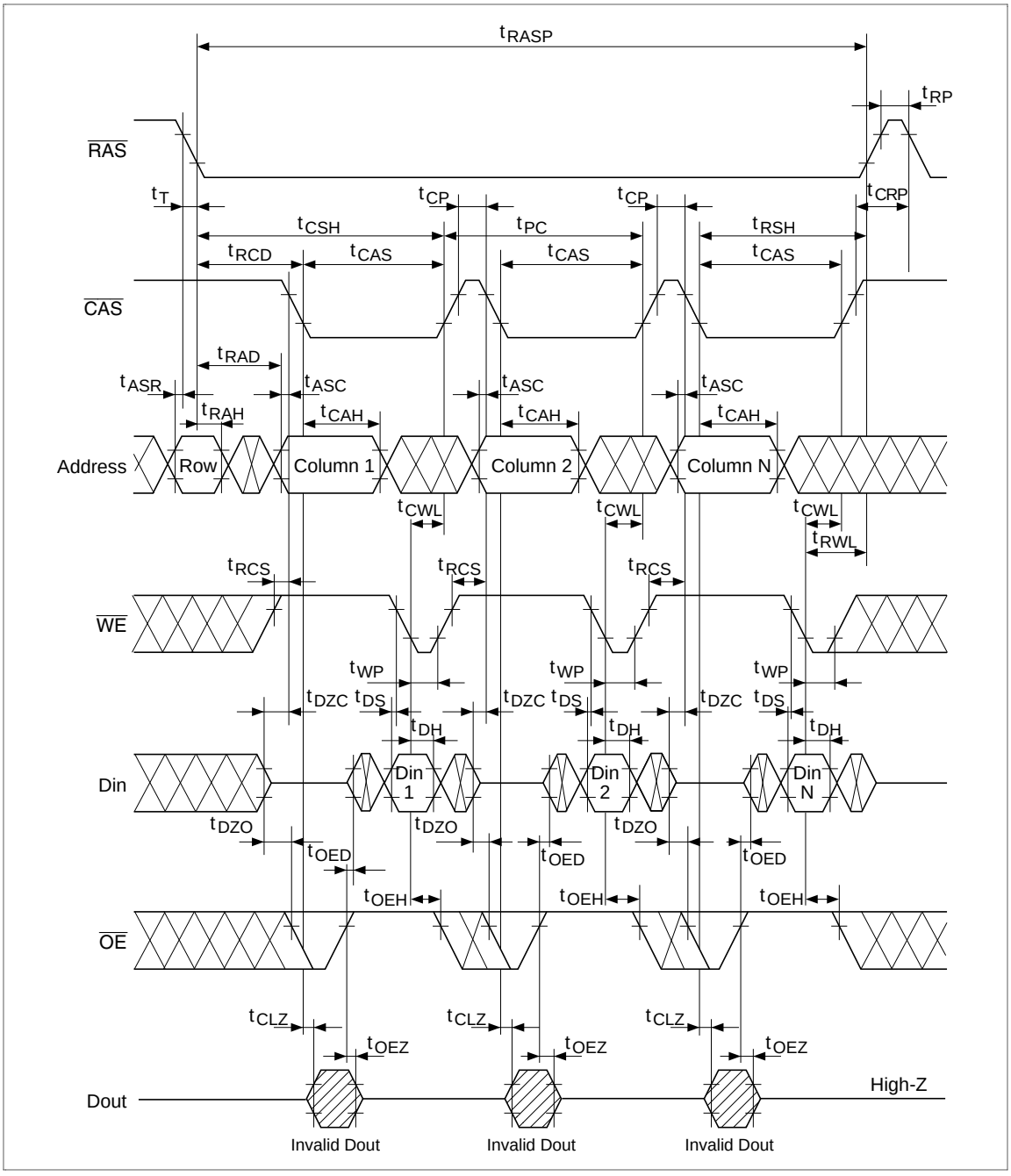
Fast Page Mode Read Cycle



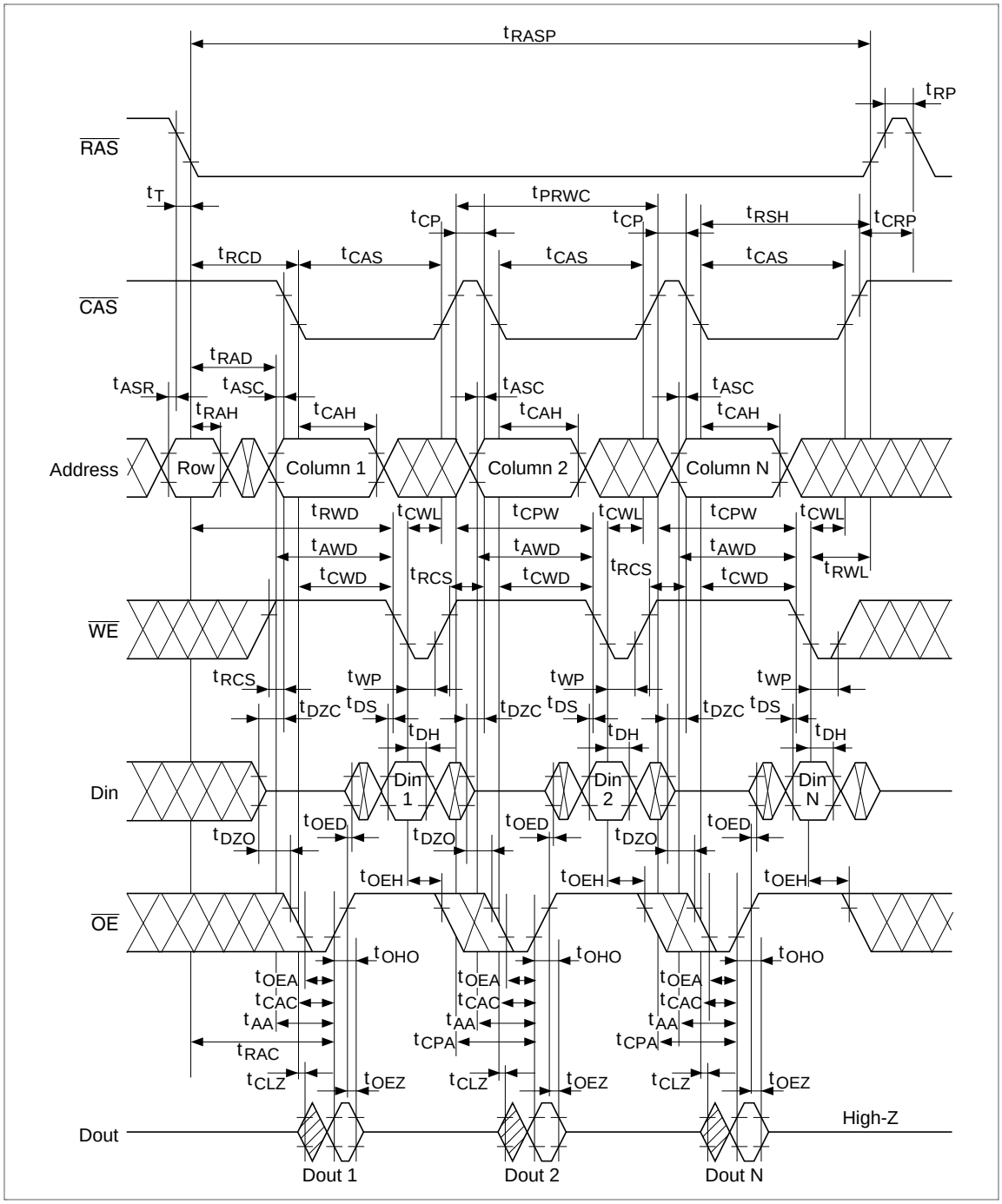
Fast Page Mode Early Write Cycle



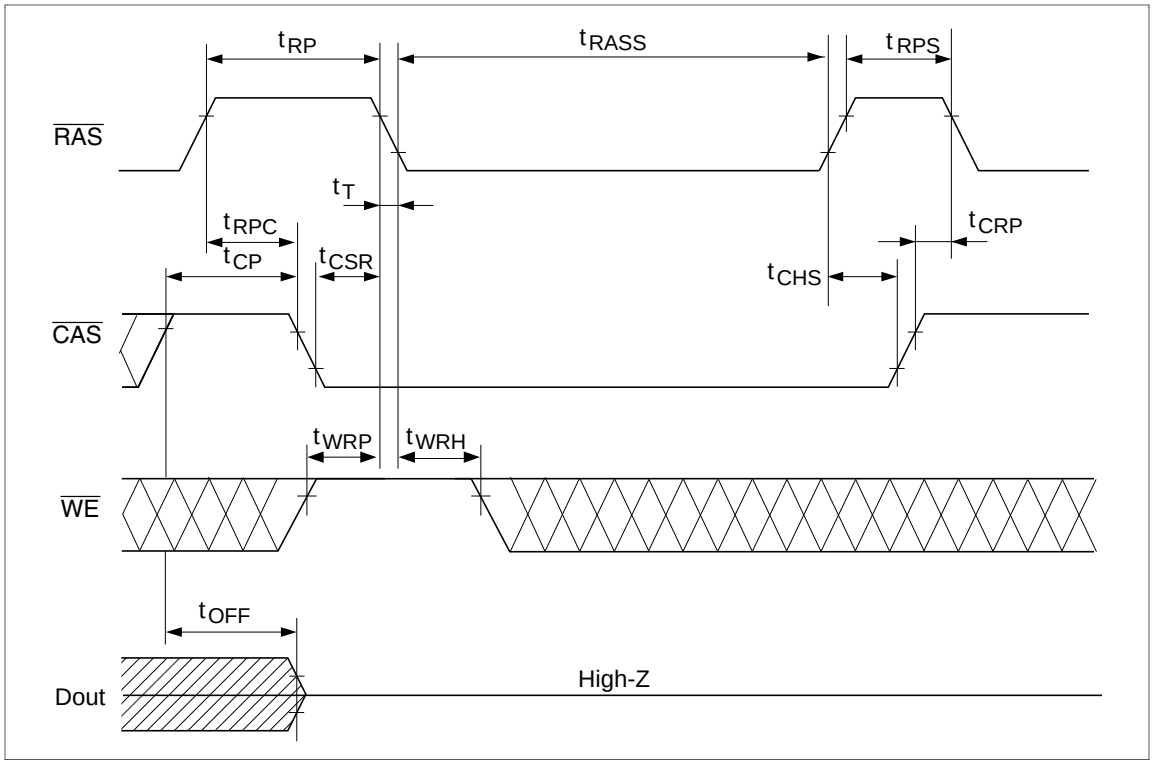
Fast Page Mode Delayed Write Cycle*[18]



Fast Page Mode Read-Modify-Write Cycle*[18]

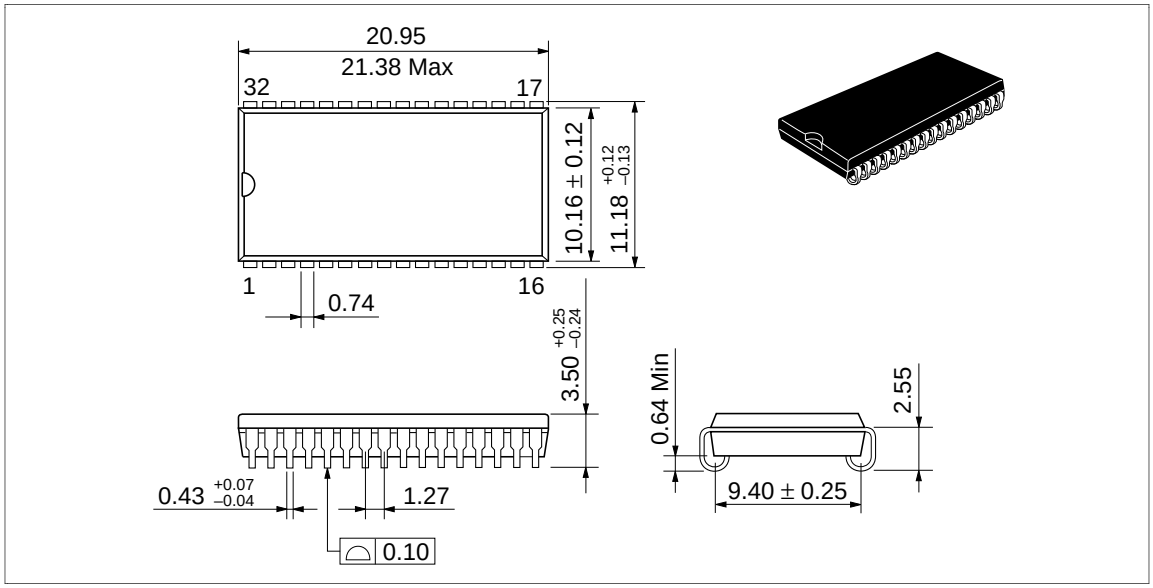


Self Refresh Cycle (L-version)*[20, 21, 22]



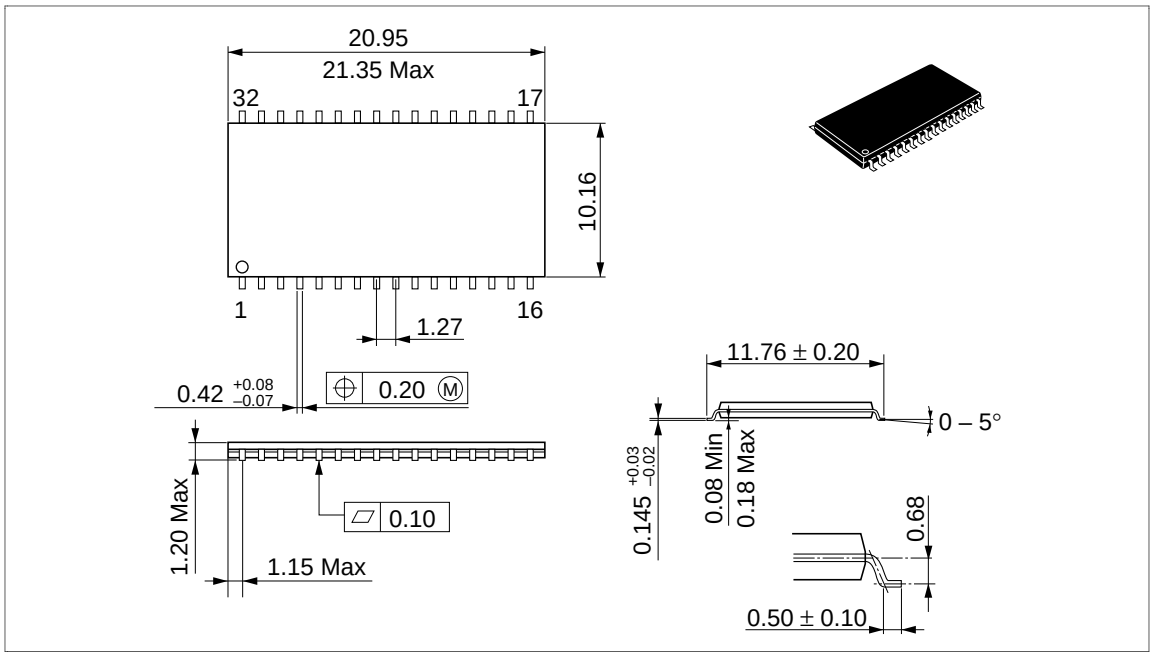
Package Dimensions

HM5164800AJ/ALJ Series
HM5165800AJ/ALJ Series (CP-32DC) Unit: mm



HM5164800ATT/ALTT Series

HM5165800ATT/ALTT Series (TTP-32DC) Unit: mm



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0.0	Jun. 3, 1996	Initial issue		